DESCRIPTION

~~POLISHING DEVICE AND WAFER POLISHING METHOD~~

TECHNICAL FIELD

[0001]

The present invention relates to an index system polishing apparatus and a wafer polishing method.

BACKGROUND ART

[0002]

A semiconductor wafer (hereinafter, also simply referred to as a wafer) typified by a silicon wafer is polished using a method for polishing the both sides at the same time or a method for polishing one side.

[0003]

In order to polish one side of the wafer, as illustrated in Figure 11, a polishing apparatus 101 configured with a turn table 104 to which a polishing pad 103 is attached, a polishing agent supplying mechanism 108 for supplying a polishing agent 107 on the turn table 104, and a polishing head 102 for holding a wafer W to be polished, is widely used.

[0004]

The polishing apparatus 101 holds the wafer W with the polishing head 102 and performs polishing by supplying the polishing agent 107 on the polishing pad 103 from the polishing agent supplying mechanism 108, while respectively rotating the turn table 104 and the polishing head 102 to bring a surface of the wafer W into sliding contact with the polishing pad 103.

[0005]

Further, the wafer is often polished through

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